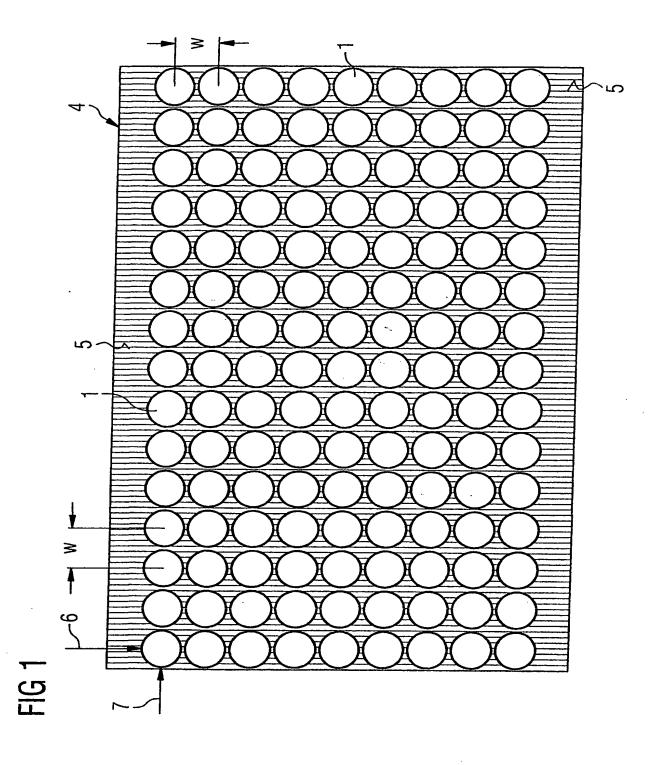
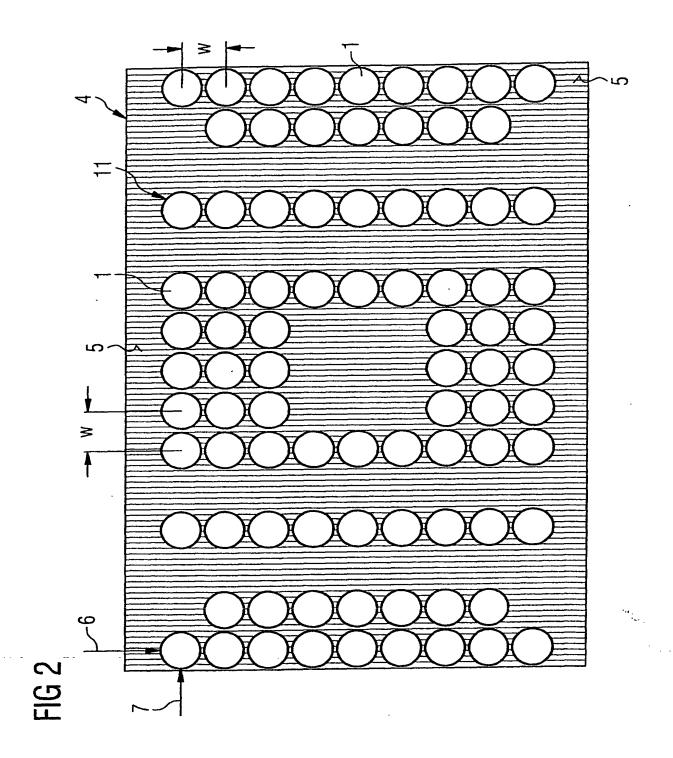
## Docket No. 1431.145.101/FIN 606 PCT/US SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING SUBSTRATES WITH SOLDER BALLS Michael Bauer et al.

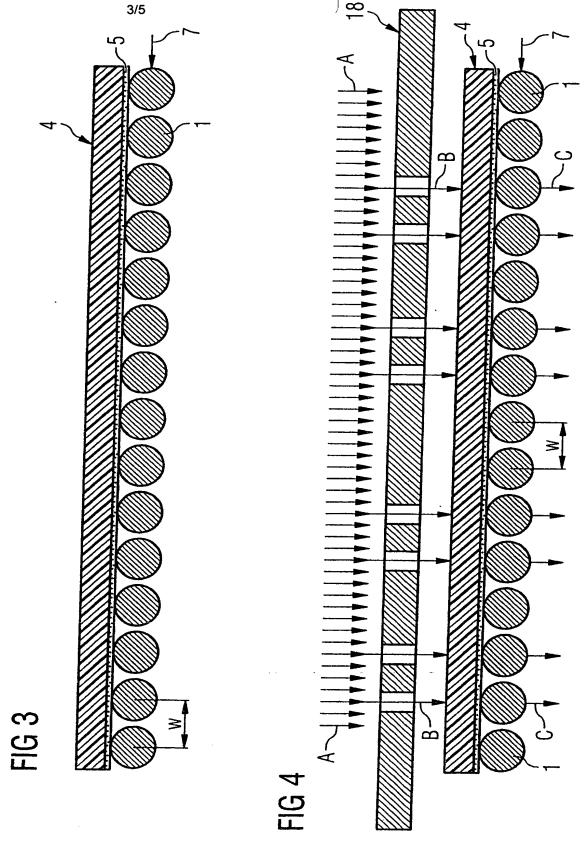




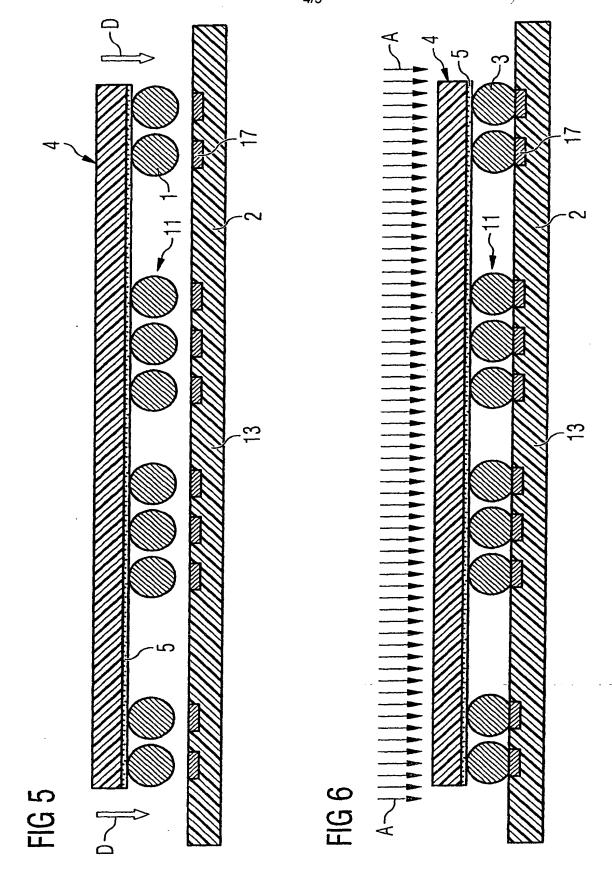
## Docket No. I431.145.101/FIN 606 PCT/US SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING SUBSTRATES WITH SOLDER BALLS Michael Bauer et al. 2/5



Docket No. 1431.145.101/FIN 606 PCT/US SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING SUBSTRATES WITH SOLDER BALLS Michael Bauer et al.



## Docket No. 1431.145.101/FIN 606 PCT/US SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING SUBSTRATES WITH SOLDER BALLS Michael Bauer et al. 4/5



## Docket No. 1431.145.101/FIN 606 PCT/US SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING SUBSTRATES WITH SOLDER BALLS Michael Bauer et al. 5/5

